



# TECHNICAL DATA SHEET

CATEGORY:  
NAME:

**ALLOY**  
**HMP (Sn5/Pb93.5/Ag1.5)**

## FEATURES

- HIGH PURITY ALLOY
- MELTING TEMPERATURE 296-301°C

## DESCRIPTION

The HMP Alloys is composed of 5% Tin, 93.5% Lead, & 2.5% Silver. This is a high purity alloy suitable for electronic applications with a melting point of 296-301°C. Typical applications are electronic assembly and high-temperature soldering applications. This alloy is available in solid and cored wire, foil, pre-forms, powder, solder paste, bar, ingot, and anode.

## IMPURITY LEVELS TO IPC-JSTD-006 in Percent

Al: 0.005	Bi: 0.10	Fe: 0.02	Sb: 0.05
As: 0.03	Cd: 0.002	In: 0.10	Zn: 0.003
Au: 0.05	Cu: 0.08	Ni: 0.01	

## MAJOR ALLOY INGREDIENTS in Percent

Sn 5% ± .5%	Ag 2.5% ± .2%	Pb Balance
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## HANDLING

- This product contains lead, which is known to be a toxic element. Consult the **Material Safety Data Sheet** for specific handling procedures.

## FLUX COMPATIBILITY

- HMP Alloy is compatible with most electronic grade fluxes.

## CLEANING

- Refer to data sheets provided by the flux manufacturer.

## SAFETY

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying **Material Safety Data Sheet** for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

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